

Form 1449 (Modified)	Atty Docket No. LAM1P177/P1139	Application No.: 10/648,953
Information Disclosure Statement By Applicant	Applicant: KANG et al.	
(Use Several Sheets if Necessary)	Filing Date August 26, 2003	Group 2823

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A1.	2005/0164479A1	07/28/05	Perng et al.			01/27/04
	A2.						
	A3.						
	A4.						
	A5.						
	A6.						
	A7.						
	A8.						
	A9.						
	A10.						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
	B1.						Yes	No
	B2.							
	B3.							
	B4.							
	B5.							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	C1.	Eric Eisenbraun et al., "Atomic Layer Deposition (ALD) of Tantalum-based Materials for Zero Thickness Copper Barrier Applications", Proceedings of IEEE (2001), pages 207-209.
	C2.	
	C3.	
	C4.	

Examiner	Date Considered
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Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.